

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: **SAW FILTER**

MODEL NO 型号: **HDBF21101A24**

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

更改历史记录  
History Record

更改日期 Date	规格书编号 Spec No	产品型号 Part No	客户产品型号 Customer No	更改内容描述 Modify Content	备注 Remark

## 1. SCOPE

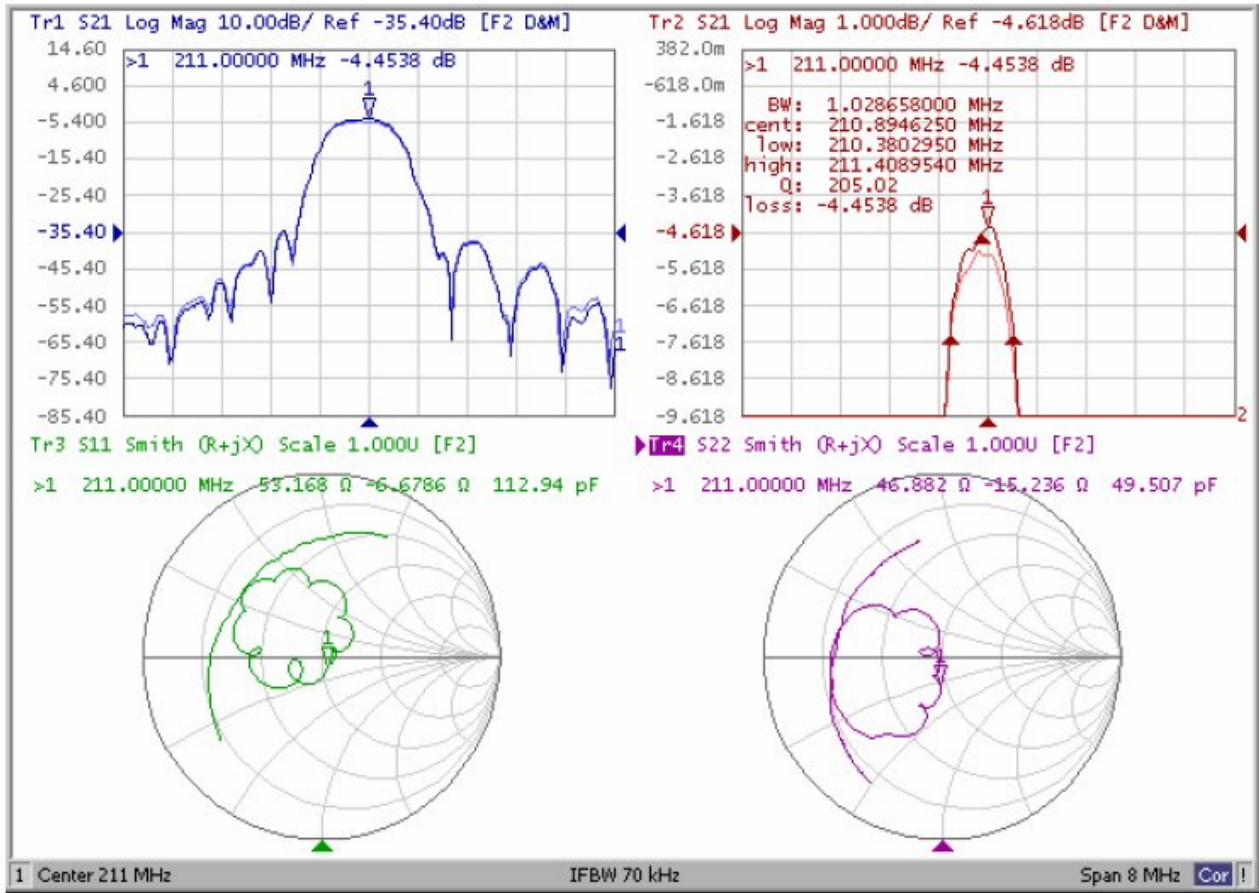
This specification shall cover the characteristics of SAW filter with HDBF21101A24 used for the page system.

## 2. ELECTRICAL SPECIFICATION

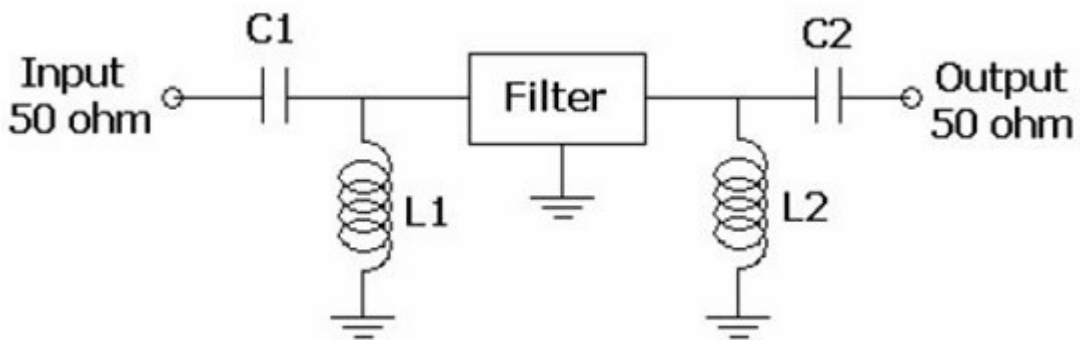
Maximum incident power in passband	+10dBm
Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40°C to +85°C
Operation temperature range	-10°C to +85°C
Suitable for lead-free soldering-Max.soldering profile	260°C for 30s

### Electronic Characteristics

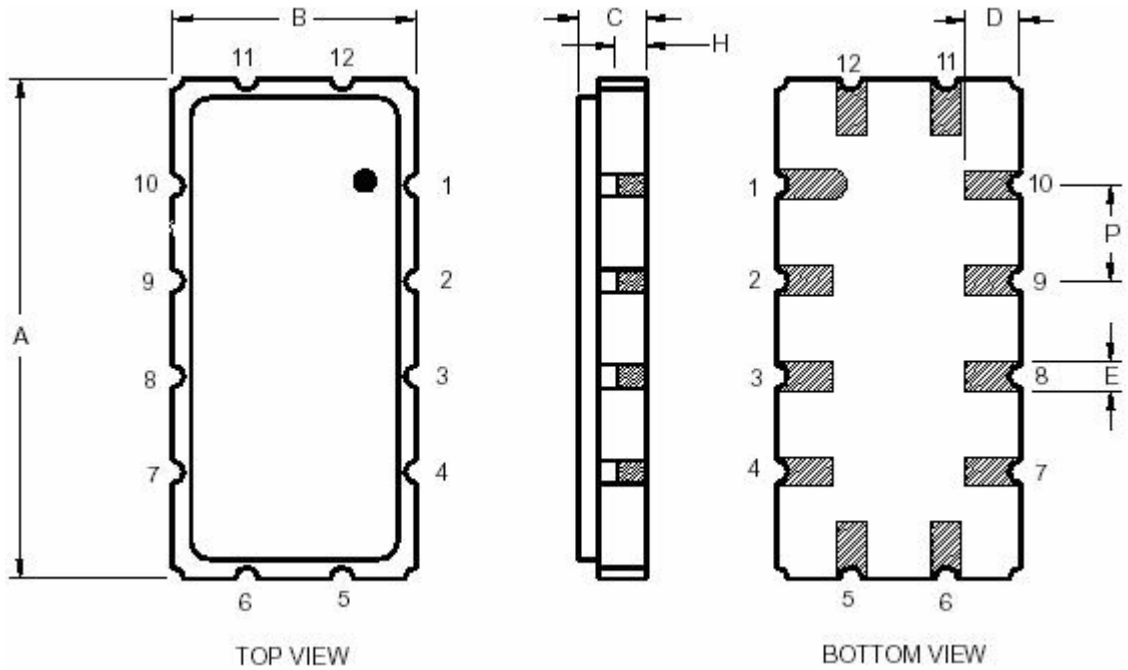
Parameter	Minimum	Typical	Maximum	Unit
Center Frequency	-	211.0	-	MHz
Insertion Loss	-	7	8	dB
3dB Bandwidth	±450	±500	-	KHz
$f_0-2.0$ to $f_0-1.05$ and $f_0+1.05$ to $f_0+2.0$ MHz	10	21	-	dB
$f_0-80$ to $f_0-2.0$ and $f_0+2.0$ to $f_0+80$ MHz	30	33	-	dB
$n \times f_0$ over 291 to 2000MHz	40	60	-	dB
Group Delay Variation over $f_0 \pm 150$ KHz		200	250	nsec
Frequency Temperature coefficient		0.32		ppm/°C



### 3. TEST CIRCUIT



**4.DIMENSION**



Dimension	mm		
	min	typ	max
A	13.1	13.3	13.5
B	6.3	6.5	6.7
C	1.21	1.36	1.51
D		1.5	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

Pin Configuration	
11	Input
5	Output
Other	Ground

## 5. ENVIRONMENTAL CHARACTERISTICS

### 5-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

### 5-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

### 5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

### 5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.